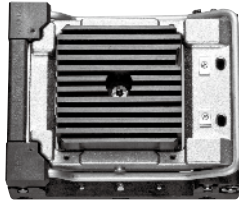


# BGA/LGA

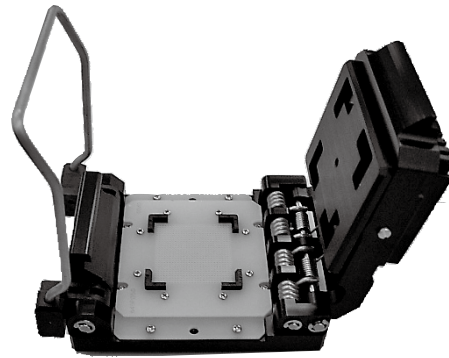
# BALL/LAND GRID ARRAY

C-series



### SPECIFICATIONS

Contact resistance: Initial 800m $\Omega$  or less (At 10 mA)  
 Maximum voltage: AC700V RMS (for 1 minute)  
 Insulation resistance: 1,000 M $\Omega$  or higher (At DC 500V)  
 Rated Current: 2A  
 Operating temperature range: -30° C ~ +150° C  
 Insertion: Min 10,000 times (Mechanical)



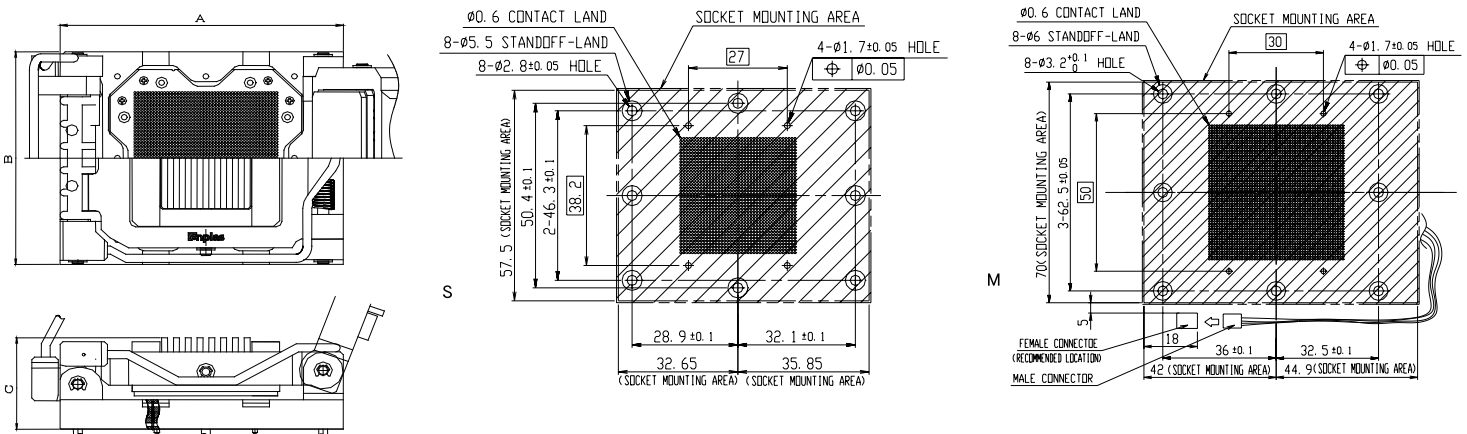
### MATERIAL

Body: Al, PES  
 Contact: Plunger/BeCu, Au plating  
 Spring/SUS, Au plating

## KEY CONCEPTS

- Flexible Pitch for 0.8mm and above, flexible pin matrix
- Unique probe pin type contact
- Compression mount
- Replaceable contact module
- RoHS compliant
- Heat-sink with high thermal performance available
- RTD sensor and heater available for thermal control
- Vertically actuated heat-sink design option for bare die

## APPLICABLE IC DIMENSIONS & SOCKET DIMENSIONS



### SOCKET LINE UP

Unit: mm

APPLICABLE IC DIMENSIONS (REF.)				OUT SIDE DIMENSIONS (REF.)			REMARKS
BODY SIZE	PITCH	GRID	MAX PIN COUNT	A	B	C	
~35	S	1.0	34	1156	68.5	57.5	Depending on HS design
		0.8	40	1600			
~45	M	1.0	44	1936	86.9	70	
		0.8	54	2916			
~55	L	1.0	49	2401	95.95	78	
~57.5	XL	1.0	56	3136	106.4	86	

If you need further details or have any questions regarding other models, please contact our local representative.

